Preferred Device

Silicon Controlled Rectifiers

Reverse Blocking Thyristors

Designed primarily for half-wave ac control applications, such as motor controls, heating controls and power supply crowbar circuits.

Features

- Glass Passivated Junctions with Center Gate Fire for Greater Parameter Uniformity and Stability
- Small, Rugged, Thermowatt Constructed for Low Thermal Resistance, High Heat Dissipation and Durability
- Blocking Voltage to 800 Volts
- 300 A Surge Current Capability
- Pb-Free Packages are Available*



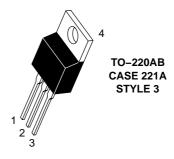
ON Semiconductor®

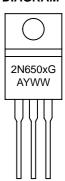
http://onsemi.com

SCRs 25 AMPERES RMS 50 thru 800 VOLTS



MARKING DIAGRAM





= 4, 5, 7, 8 or 9

= Assembly Location

= Year

WW = Work Week

G = Pb-Free Device

PIN ASSIGNMENT		
1	Cathode	
2	Anode	
3	Gate	
4	Anode	

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 6 of this data sheet.

Preferred devices are recommended choices for future use and best overall value.

^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

MAXIMUM RATINGS (T_J = 25°C unless otherwise noted)

Rating	Symbol	Value	Unit
*Peak Repetitive Off–State Voltage (Note 1) (Gate Open, Sine Wave 50 to 60 Hz, T _J = 25 to 125°C) 2N6504 2N6505 2N6507 2N6508 2N6509	V _{DRM,} V _{RRM}	50 100 400 600 800	V
On-State Current RMS (180° Conduction Angles; T _C = 85°C)	I _{T(RMS)}	25	Α
Average On-State Current (180° Conduction Angles; T _C = 85°C)	I _{T(AV)}	16	Α
Peak Non-repetitive Surge Current (1/2 Cycle, Sine Wave 60 Hz, T _J = 100°C)	I _{TSM}	250	Α
Forward Peak Gate Power (Pulse Width ≤ 1.0 μs, T _C = 85°C)	P _{GM}	20	W
Forward Average Gate Power (t = 8.3 ms, T _C = 85°C)	P _{G(AV)}	0.5	W
Forward Peak Gate Current (Pulse Width ≤ 1.0 μs, T _C = 85°C)	I _{GM}	2.0	Α
Operating Junction Temperature Range	TJ	-40 to +125	°C
Storage Temperature Range	T _{stg}	-40 to +150	°C

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

Characteristic		Max	Unit
*Thermal Resistance, Junction-to-Case		1.5	°C/W
*Maximum Lead Temperature for Soldering Purposes 1/8 in from Case for 10 Seconds		260	°C

Characteristic	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS					
*Peak Repetitive Forward or Reverse Blocking Current $(V_{AK} = Rated \ V_{DRM} \ or \ V_{RRM}, \ Gate \ Open)$ $T_J = 25^{\circ}C$ $T_J = 125^{\circ}C$	I _{DRM} , I _{RRM}	_ _	_ _	10 2.0	μA mA
ON CHARACTERISTICS					
*Forward On-State Voltage (Note 2) (I _{TM} = 50 A)	V_{TM}	_	-	1.8	V
* Gate Trigger Current (Continuous dc) $T_C = 25^{\circ}C$ $(V_{AK} = 12 \text{ Vdc}, R_L = 100 \Omega)$ $T_C = -40^{\circ}C$	I _{GT}	- -	9.0	30 75	mA
*Gate Trigger Voltage (Continuous dc) ($V_{AK} = 12 \text{ Vdc}, R_L = 100 \Omega, T_C = -40^{\circ}\text{C}$)	V _{GT}	_	1.0	1.5	V
Gate Non-Trigger Voltage (V_{AK} = 12 Vdc, R_L = 100 Ω , T_J = 125°C)	V_{GD}	0.2	_	-	V
*Holding Current $T_C = 25^{\circ}C$ (V _{AK} = 12 Vdc, Initiating Current = 200 mA, Gate Open) $T_C = -40^{\circ}C$	I _H	- -	18 -	40 80	mA
*Turn-On Time (I _{TM} = 25 A, I _{GT} = 50 mAdc)	t _{gt}	_	1.5	2.0	μs
Turn-Off Time (V_{DRM} = rated voltage) (I_{TM} = 25 A, I_R = 25 A) (I_{TM} = 25 A, I_R = 25 A, T_J = 125°C)	t _q	- -	15 35	- -	μS
DYNAMIC CHARACTERISTICS					
Critical Rate of Rise of Off-State Voltage (Gate Open, Rated V _{DRM} , Exponential Waveform)	dv/dt	_	50	_	V/μs

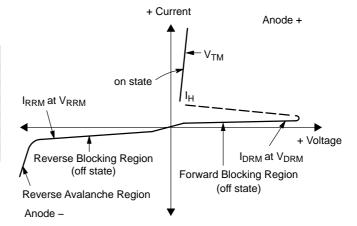
^{*}Indicates JEDEC Registered Data.

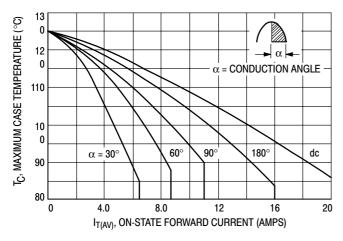
V_{DRM} and V_{RRM} for all types can be applied on a continuous basis. Ratings apply for zero or negative gate voltage; however, positive gate voltage shall not be applied concurrent with negative potential on the anode. Blocking voltages shall not be tested with a constant current source such that the voltage ratings of the devices are exceeded.

^{2.} Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2%.

Voltage Current Characteristic of SCR

Symbol	Parameter
V_{DRM}	Peak Repetitive Off State Forward Voltage
I _{DRM}	Peak Forward Blocking Current
V_{RRM}	Peak Repetitive Off State Reverse Voltage
I _{RRM}	Peak Reverse Blocking Current
V_{TM}	Peak On State Voltage
IH	Holding Current





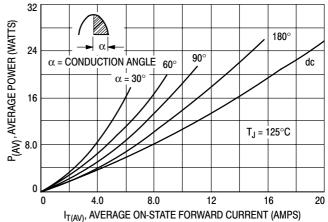
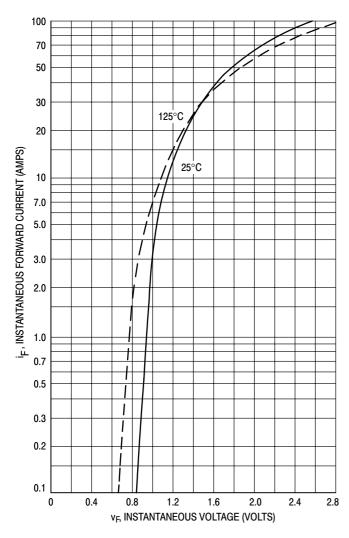


Figure 1. Average Current Derating

Figure 2. Maximum On-State Power Dissipation



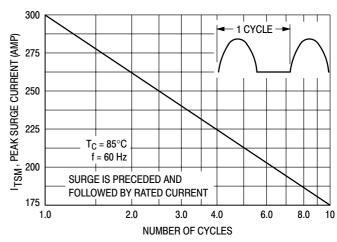


Figure 3. Typical On-State Characteristics

Figure 4. Maximum Non-Repetitive Surge Current

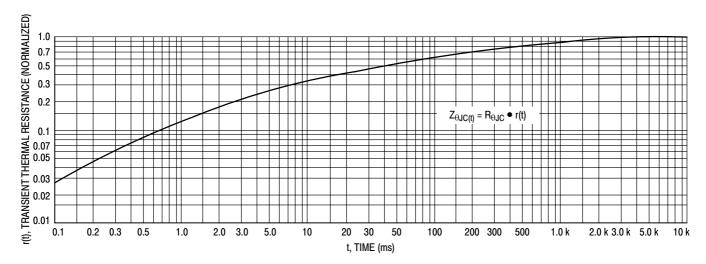


Figure 5. Thermal Response

TYPICAL TRIGGER CHARACTERISTICS

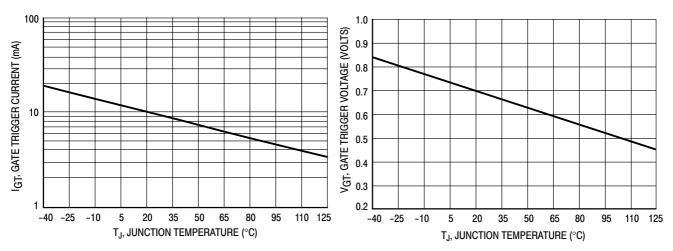


Figure 6. Typical Gate Trigger Current versus Junction Temperature

Figure 7. Typical Gate Trigger Voltage versus Junction Temperature

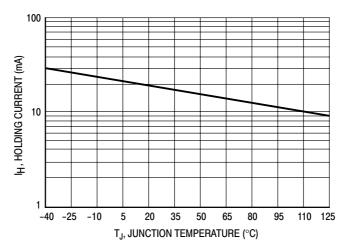


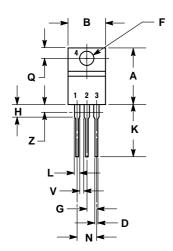
Figure 8. Typical Holding Current versus Junction Temperature

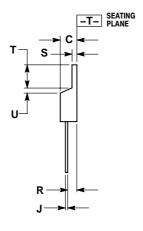
ORDERING INFORMATION

Device	Package	Shipping
2N6504	TO-220AB	
2N6504G	TO-220AB (Pb-Free)	
2N6505	TO-220AB	
2N6505G	TO-220AB (Pb-Free)	
2N6505T	TO-220AB	
2N6505TG	TO-220AB (Pb-Free)	
2N6507	TO-220AB	
2N6507G	TO-220AB (Pb-Free)	FOO Haite (Page
2N6507T	TO-220AB	500 Units / Box
2N6507TG	TO-220AB (Pb-Free)	
2N6508	TO-220AB	
2N6508G	TO-220AB (Pb-Free)	
2N6509	TO-220AB	
2N6509G	TO-220AB (Pb-Free)	
2N6509T	TO-220AB	
2N6509TG	TO-220AB (Pb-Free)	

PACKAGE DIMENSIONS

TO-220AB CASE 221A-09 ISSUE AA





NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: INCH.
- DIMENSION Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE ALLOWED.

	INCHES		INCHES MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
Α	0.570	0.620	14.48	15.75
В	0.380	0.405	9.66	10.28
С	0.160	0.190	4.07	4.82
D	0.025	0.035	0.64	0.88
F	0.142	0.147	3.61	3.73
G	0.095	0.105	2.42	2.66
Н	0.110	0.155	2.80	3.93
Ĺ	0.018	0.025	0.46	0.64
K	0.500	0.562	12.70	14.27
L	0.045	0.060	1.15	1.52
N	0.190	0.210	4.83	5.33
Q	0.100	0.120	2.54	3.04
R	0.080	0.110	2.04	2.79
S	0.045	0.055	1.15	1.39
T	0.235	0.255	5.97	6.47
U	0.000	0.050	0.00	1.27
٧	0.045		1.15	
Z		0.080		2.04

STYLE 3:

PIN 1. CATHODE

- 2. ANODE
- 3. GATE
- 4. ANODE

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